

CP373-CMPDM303NH **N-Channel MOSFET Die Enhancement-Mode**

The CP373-CMPDM303NH is a silicon N-Channel MOSFET designed for high speed pulsed amplifier and driver applications.

		MECHANICA	L SPECIFICAT	IONS:		
G BACKSIDE DRAIN		Die Size		39 x 27 MILS		
		Die Thickness		7.5 MILS		
		Gate Bonding Pad Size		6.5 x 6.5 MILS		
		Source Bonding Pad Size		33 x 21 MILS		
		Top Side Metalization		AI – 40,000Å		
		Back Side Metalization		Ti/Ni/Ag – 1,000Å/3,000Å/10,000Å		
		Scribe Alley Width		3.15 MILS		
		Wafer Diameter		8 INCHES		
		Gross Die Per Wafer		43,500		
MAXIMUM RAT	INGS: (T _A =25°C)		SYMBOL			UNITS
	Drain-Source Voltage		V _{DS}	30		V
Gate-Source Vo	Itage		V _{GS}	12		V
Continuous Drai	n Current (Steady	State)	۱ _D	3.6	6	А
Maximum Pulse	d Drain Current, tp	=10µs	IDM	14.	4	А
Operating and S	torage Junction Te	emperature	TJ, Tstg	-55 to [.]	+150	°C
ELECTRICAL C	HARACTERISTIC	S: (T∧=25°C u	nless otherwise	e noted)		
SYMBOL	TEST CONDITIC		MIN		MAX	UNITS
I _{GSSF} , I _{GSSR}	V _{GS} =12V, V _{DS} =0				10	μA
IDSS	V _{DS} =20V, V _{GS} =0				1.0	μA
BVDSS	V _{GS} =0, I _D =250µA		30			V
V _{GS(th)}	V _{GS} =V _{DS} , I _D =250µA		0.6		1.2	V
rDS(ON)	V _{GS} =4.5V, I _D =1.8A				0.04	Ω
^r DS(ON)	V _{GS} =2.5V, I _D =1.8A				0.078	Ω
9FS	V _{DS} =5.0V, I _D =3.6A			11.8		S
C _{rss}	V _{DS} =10V, V _{GS} =0, f=1.0MHz			55		pF
C _{iss}	V _{DS} =10V, V _{GS} =	0, f=1.0MHz		590		pF
C _{oss}	V _{DS} =10V, V _{GS} =0, f=1.0MHz			50		pF
Q _{g(tot)}	V _{DD} =10V, V _{GS} =	=4.5V, I _D =3.6A			13	nC
Q _{gs}	V _{DD} =10V, V _{GS} =	=4.5V, I _D =3.6A			1.4	nC
Q _{gd}	V _{DD} =10V, V _{GS} =	=4.5V, I _D =3.6A			2.7	nC
t _{on}	V _{DD} =10V, V _{GS} =	=4.0V, I _D =3.6A	, R _G =10Ω	15		ns
toff	V _{DD} =10V, V _{GS} =	, R _G =10Ω	29		ns	

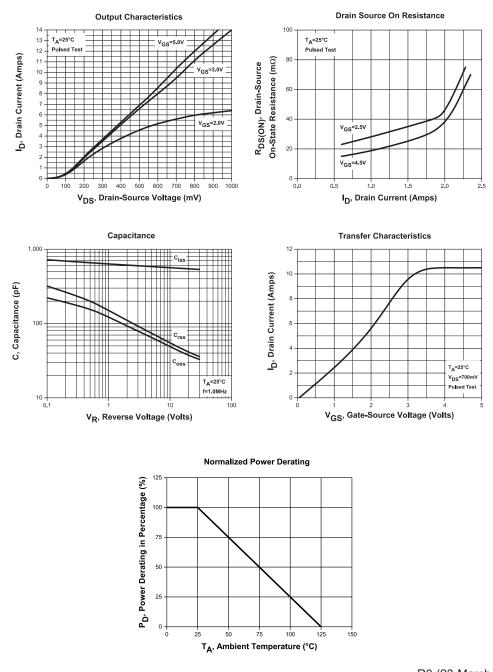
MEQUANICAL OPECIFICATIONS

R0 (23-March 2018)

CP373-CMPDM303NH Typical Electrical Characteristics



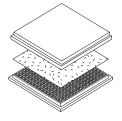
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BARE DIE PACKING OPTIONS



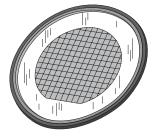


BARE DIE IN TRAY (WAFFLE) PACK

- CT: Singulated die in tray (waffle) pack. (example: CP211-PART NUMBER-CT)
- CM: Singulated die in tray (waffle) pack 100% visually inspected as per MIL-STD-750, (method 2072 transistors, method 2073 diodes). (example: CP211-<u>PART NUMBER</u>-CM)

UNSAWN WAFER

WN: Full wafer, unsawn, 100% tested with reject die inked. (example: CP211-PART NUMBER-WN)



SAWN WAFER ON PLASTIC RING

WR: Full wafer, sawn and mounted on plastic ring, 100% tested with reject die inked. (example: CP211-PART NUMBER-WR)

Please note: Sawn Wafer on Metal Frame (WS) is possible as a special order. Please contact your Central Sales Representative at 631-435-1110.



Visit the Central website for a complete listing of specifications: www.centralsemi.com/bdspecs

OUTSTANDING SUPPORT AND SUPERIOR SERVICES

PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free guick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- · Environmental regulation compliance
- Customer specific screening
- · Up-screening capabilities

· Custom product packing

Custom bar coding for shipments

- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- · Application and design sample kits
- · Custom product and package development

REQUESTING PRODUCT PLATING

- If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when 1. ordering (example: 2N2222A TIN/LEAD).
- 2. If requesting Lead (Pb) Free plated devices, add the suffix " PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

Corporate Headquarters & Customer Support Team

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http://www.centralsemi.com

Product End of Life Notification

PDN ID:	PDN01124
Notification Date:	4/18/19
Last Buy Date:	10/18/19
Last Shipment Date	4/18/20

Summary: The CP373 wafer process is being discontinued and is now classified as End of Life (EOL). The replacement wafer process is CP398X.

Although Central Semiconductor Corp. makes every effort to continue to produce devices that have been proclaimed EOL (End of Life) by other manufacturers, it is an accepted industry practice to discontinue certain devices when customer demand falls below a minimum level of sustainability. Accordingly, the following product(s) have been transitioned to End of Life status as part of Central's ongoing Product Management Process. Any replacement products are noted below. The effective date for placing last purchase orders will be six (6) months from the date of this notice and twelve (12) months from the notice date for final shipments, and minimum order quantities may apply. The last purchase and shipment dates may be extended if inventory is available.

Central Part Number	Replacement
CP373-CMPDM303-CT20	CP398X-CPDM303-CT20
CP373-CMPDM303NH-CT	CP398X-CPDM303NH-CT
CP373-CMPDM303NH-WN	CP398X-CPDM303NH-WN
CP373-CTLDM303N-CT	CP398X-CTLDM303N-CT
CP373-CTLDM303N-WN	CP398X-CTLDM303N-WN

Central would be happy to assist you by providing additional information or technical data to help locate an alternate source if we have no replacement available. Please email your requests to engineering@centralsemi.com.

DISCLAIMER: This End of Life (EOL) notification is in accordance with JEDEC standard JESD48 - Product Discontinuance. Central Semiconductor Corp. will make every effort to offer life-time buy (LTB) opportunities and/or offer replacement devices to existing customers for discontinued devices, however, one or both may not be possible for all devices. Please contact your local Central Semiconductor sales representative for LTB opportunities/additional information.